MECHANICAL DATA

MCDI004A - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL-IN-LINE PACKAGE

J (R-GDIP-T**)



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
- D. This package can be hermetically sealed with a ceramic lid using glass frit.
- E. Index point is provided on cap for terminal identification.



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